

LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC1553CSW#PBF

(Engineering Calculation)

SOC WIDE

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TOTAL MASS (g): 0.543708

COMPONENT MATERIAL	VENDOR/INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL Pkg.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000000	1000000	10014.6337891		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.153163	975000	281700.96875		
		Iron (Fe)	7439-89-6	0.003770	24000	6931.87255859		
		Phosphorus (P)	7723-14-0	0.000047	300	86.443504335		
		Zinc (Zn)	7440-66-6	0.000110	700	202.314575195		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		<b>Lead Frame Total:</b>				<b>0.157090</b>	<b>1000000</b>	<b>280923.59375</b>
		Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0
Exter. Plating Sn	7440-31-5			0.000974	1000000	10986.9267578		
<b>External Plating Total:</b>						<b>0.000974</b>	<b>1000000</b>	<b>10986.9267578</b>
Inter. Plating Ni	7440-02-0			0.000000	0	0		
Inter. Plating Ag	7440-22-4			0.001257	1000000	2311.90405273		
<b>Internal Plating Total:</b>						<b>0.001257</b>	<b>1000000</b>	<b>2311.90405273</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001471	750000	2705.49755859		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000490	250000	901.219482422		
		<b>Die Attach Total:</b>				<b>0.001961</b>	<b>1000000</b>	<b>3606.7172816</b>
		Encapsulation	MULTIAROMATIC RESIN BUSH FREE	Resin (EP)		0.038213	103000	70282.2421875
				Bromine (Br)	40093-93-8	0.000000	0	0
Silica (SiO2)	60676-86-0			0.332045	895000	610704.875		
Antimony Trioxide (Sb2O3)	1309-64-4			0.000000	0	0		
Metal Hydroxide				0.000000	0	0		
Carbon Black (C)	1333-86-4			0.000742	2000	1364.70373535		
<b>Encapsulation Total:</b>						<b>0.371000</b>	<b>1000000</b>	<b>682351.875</b>
Bond Wire Estimated	AFW/TANAKA/Kn	Gold (Au)	7440-57-5	0.000546	1000000	1004.21600342		

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